

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	99	("6165885").URPN.	USPAT	OR	OFF	2009/03/02 09:48
L2	168	(particles NEAR4 shape) and flake\$3 and solder\$3	USPAT	OR	OFF	2009/03/02 09:51
L3	158	(particles NEAR4 shape) and flake\$3 and solder\$3 and conduct\$5	USPAT	OR	OFF	2009/03/02 09:52
L4	138	(particles NEAR3 shape) and flake\$3 and solder\$3 and conduct\$5	USPAT	OR	OFF	2009/03/02 09:52
S1	4	"1085729"	US-PGPUB; USPAT	ADJ	ON	2008/11/04 14:58
S2	1	"10585729"	US-PGPUB; USPAT	ADJ	ON	2008/11/04 14:59
S3	4118	(228/111.5) or (228/208) or (228/262.45) or (438/612)	US-PGPUB; USPAT	ADJ	ON	2008/11/04 16:03
S4	2705847	(flux or paste) or solder\$3 or electrode or (heat or reflow) or (powder or particle\$2) or surface NEAR4 metal or core NEAR4 metal	US-PGPUB; USPAT	ADJ	ON	2008/11/04 16:05
S5	3839	S3 and S4	US-PGPUB; USPAT	ADJ	ON	2008/11/04 16:06
S6	382	(flux or paste) and solder\$3 and electrode and (heat or reflow) and (powder or particle \$2) and surface NEAR4 metal and core NEAR4 metal	US-PGPUB; USPAT	ADJ	ON	2008/11/04 16:07
S7	382	S6 and (method or process)	US-PGPUB; USPAT	ADJ	ON	2008/11/04 16:09
S8	13	S6 and (resin or rosin) and activator	US-PGPUB; USPAT	ADJ	ON	2008/11/04 16:09

S9	3605195	(flux or paste) or solder\$3 or electrode or (heat or reflow) or (powder or particle\$2) and metal and bump	EPO; JPO; DERWENT	ADJ	ON	2008/11/04 16:43
S10	24	(flux or paste) and solder\$3 and electrode and (heat or reflow) and (powder or particle \$2) and metal and bump	EPO; JPO; DERWENT	ADJ	ON	2008/11/04 16:44
S11	5	((("5019187") or ("4333669") or ("4273593") or ("3904328") or ("3829944")).PN.	USPAT; USOCR	OR	OFF	2008/11/04 16:58
S12	10035	solder near bump	USPAT	ADJ	ON	2008/11/05 09:14
S13	840	"29".clas. and solder NEAR2 bump	USPAT	ADJ	ON	2008/11/05 09:15
S14	5	"29".clas. and solder NEAR2 bump and (rosin or resin) and activator	USPAT	ADJ	ON	2008/11/05 09:29
S15	7	("5328087" "5445308" "6335563" "6368895" "6524943" "6621172" "6670264").PN. OR ("6796025").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/05 09:34
S16	0	"29".clas. and solder NEAR2 bump and suface NEAR2 metal and core NEAR2 metal	USPAT	ADJ	ON	2008/11/05 09:43
S17	0	"29".clas. and solder NEAR2 bump and suface NEAR2 metal	USPAT	ADJ	ON	2008/11/05 09:43
S18	0	"29".clas. and solder NEAR2 bump and suface NEAR2 metal	US-PGPUB; USPAT	ADJ	ON	2008/11/05 09:43
S19	0	"29".clas. and solder NEAR2 bump and suface NEAR4 metal	US-PGPUB; USPAT	ADJ	ON	2008/11/05 09:44

S20	11	US-20020185309-\$. DID. OR US- 20040126094-\$. DID. OR US- 20010051535-\$. DID. OR US- 1178711-\$.DID. OR US-6315790-\$.DID. OR US-1111994-\$. DID. OR US- 5261586-\$.DID. OR US-1051119-\$.DID.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/05 10:09
S21	6	"6680128"	USPAT	ADJ	ON	2008/11/05 10:44
S22	1	("6680128").PN.	USPAT; USOCR	OR	OFF	2008/11/05 10:44
S23	1	("6189771").PN.	USPAT; USOCR	OR	OFF	2008/11/05 10:47
S24	0	"10590473"	USPAT	ADJ	ON	2008/11/05 10:49
S25	1	"10590473"	US-PGPUB; USPAT	ADJ	ON	2008/11/05 10:50
S26	11	"6951666"	US-PGPUB; USPAT	ADJ	ON	2008/11/05 10:53
S27	1	("6951666").PN.	USPAT; USOCR	OR	OFF	2008/11/05 10:53

3/ 2/ 2009 9:53:51 AM

**C:\ Documents and Settings\ aabdelrahman\ My Documents\ EAST\ Workspaces\ Workspaces
 \ 10585729.wsp**